

MATERIAL DECLARATION

RTR SERIES

 RTR50-H

NO	BREAKDOWN OF PART	MANUFACTURER	MATERIAL NAME	CHEMICAL SYMBOL	CAS NO.	%	TOTAL		1.5140	
							WEIGHT	SUBSTANCE MASS. (Mg)	%	SUBSTANCE %
1	Alumina Substrate	Leatec Fine Ceramics	Al2O3 substrate	Al2O3	1344-28-1	96.00	146.00	140.160	9.643	9.2576
				SiO2	14808-60-7	3.00		4.380		0.2893
				MgO	1309-48-4	1.00		1.460		0.0964
2	Resistor Layer	SUMITOMO	Resistive	Silver	744-22-4	30.00	60.00	18.000	3.963	1.1889
				Paste	744-05-3	10.00		6.000		0.3963
				Puthenium Oxide	12036-10-1	10.00		6.000		0.3963
				Lead Oxide	1317-36-8	15.00		9.000		0.5945
				Boron Trioxide	1303-86-2	2.00		1.200		0.0793
				Aluminium Oxide	1344-28-1	2.00		1.200		0.0793
				Silicon Dioxide	7631-86-9	10.00		6.000		0.3963
				Zinc Oxide	1314-13-2	2.00		1.200		0.0793
				Copper Oxide	1317-38-0	0.50		0.300		0.0198
				Manganese Oxide	1317-35-7	1.50		0.900		0.0594
				Tantalum Oxide	1314-61-0	1.50		0.900		0.0594
				Titanium Dioxide	13463-67-7	0.50		0.300		0.0198
				Terpineol	8000-41-7	10.00		6.000		0.3963
Dibutyl Decanedioate	109-43-3	5.00	3.000	0.1982						
3	Flange	HCT	Lead Frame	Cu	7440-50-8	100.00	98.00	98.000	6.473	6.4729
4	Solder	SHENMAO	Lead-free solder	Sn	7440-31-5	94.30	105.00	99.015	6.935	6.5400
				Ag	7440-22-4	3.00		3.150		0.2081
				Cu	7440-50-8	0.50		0.525		0.0347
				Rosin	8050-09-7	2.00		2.100		0.1387
				Activator	Not Established	0.10		0.105		0.0069
				Others	Not Established	0.10		0.105		0.0069
				Crystalline Silica	14808-60-7	72.50		801.125		72.985
5	Molding	ETERNAL	Epoxy Resin	Fused Silica	60676-86-0	10.00	110.500	72.985	7.2985	
				Epoxy Resin	29690-82-2	10.00	110.500		7.2985	
				Phenol Resin	9003-35-4	5.00	55.250		3.6493	
				Metal hydroxide	-	2.00	22.100		1.4597	
				Carbon Black	1333-86-4	0.50	5.525		0.3649	

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